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Clie	ent Name						
C	 Client P/N						
Pro)5-D1-I \/RQ(Δι.1				
Send	HL-C3535F9V395-D1-LVR9(Au120) Sending Date						
Client a	approval	Hongli approval					
Approval	Audit	Approval	Audit	Confirmation			
Qualified	Disqualified	DATE:	6. 05. 16				
Adr NO.1,Xi anke Yi Road,Huadong Town,, Huadu District, Guangzhou, China 1							
Tel / 020-867 Web/ www.hon	33333 Fax/ glitronic.com	020-8673388	83 86733938	86733265			
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- 1. Product naming rules
- 2. Features
- 3. Application range
- 4. Radiation Pattern

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- **5.Typical Optical/Electrical Characteristics Curves**
- 6.Absolute Maximum Ratings
- 7. Package Dimensions
- 8. Welded plate Dimensions
- 9.Label
- **10.Tape Specifications**
- **11.Reflow soldering instructions**
- 12.Use the matters needing attention





Application range

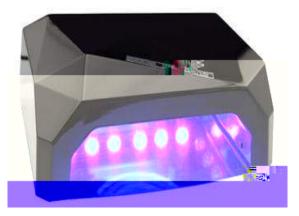




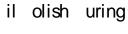
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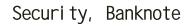








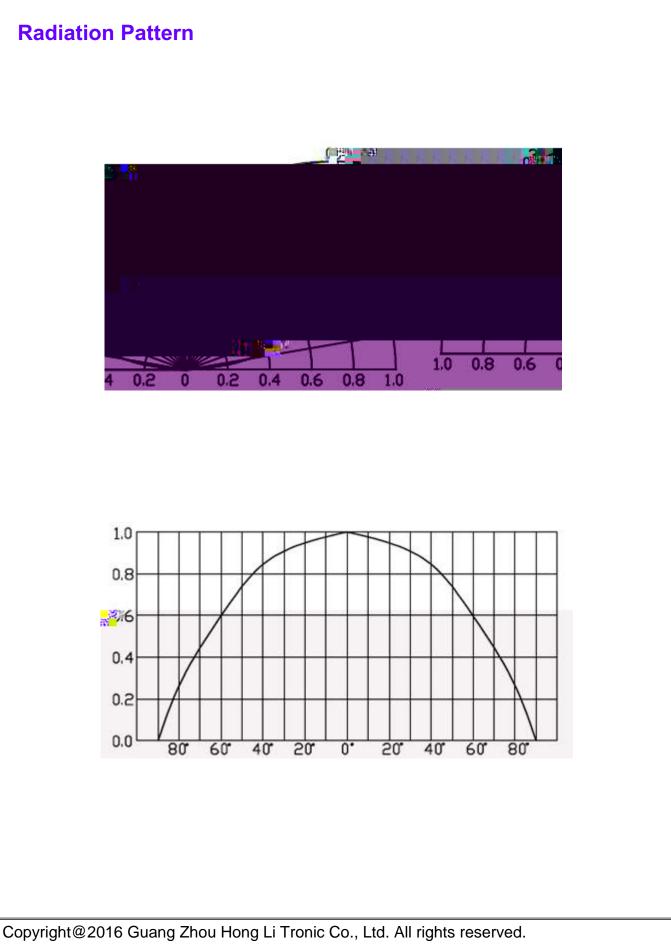






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Typical Optical/Electrical Characteristics @Ta=25§7 HmdY

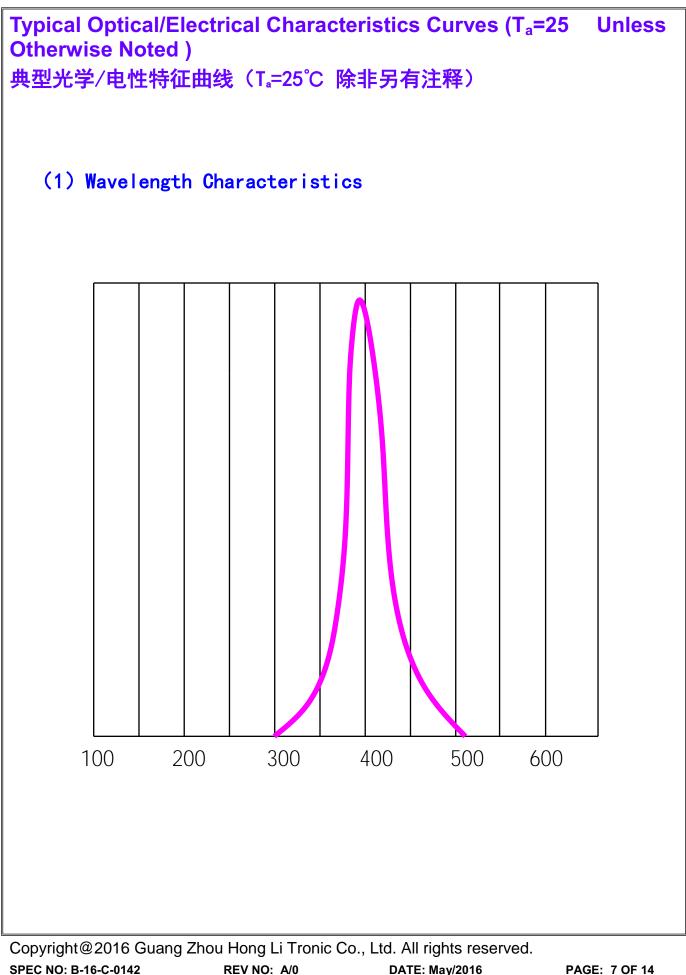
Symbol	ltem	Min.	Тур.	Max.	Units	Test Conditions
е	Radiation Flux辐射功率	700	800		mW	IF=500mA
VF	Forward Voltage 正向电压	3.0	_	3.8	V	IF=500mA
Ρ	Peak Wavelength	390	_	400	nm	IF=500mA
2 1/2	50% Power Angle	_	120	_	deg	IF=500mA
IR	Reverse Current	_	_	50	uA	VR = 5V
L50	Life Time	5000	_	_	Hour	IF=500mA
L50	Life Time	_	3000	_	Hour	IF=700mA

Absolute Maximum Ratings 绝对最大额定值@H51&) š7

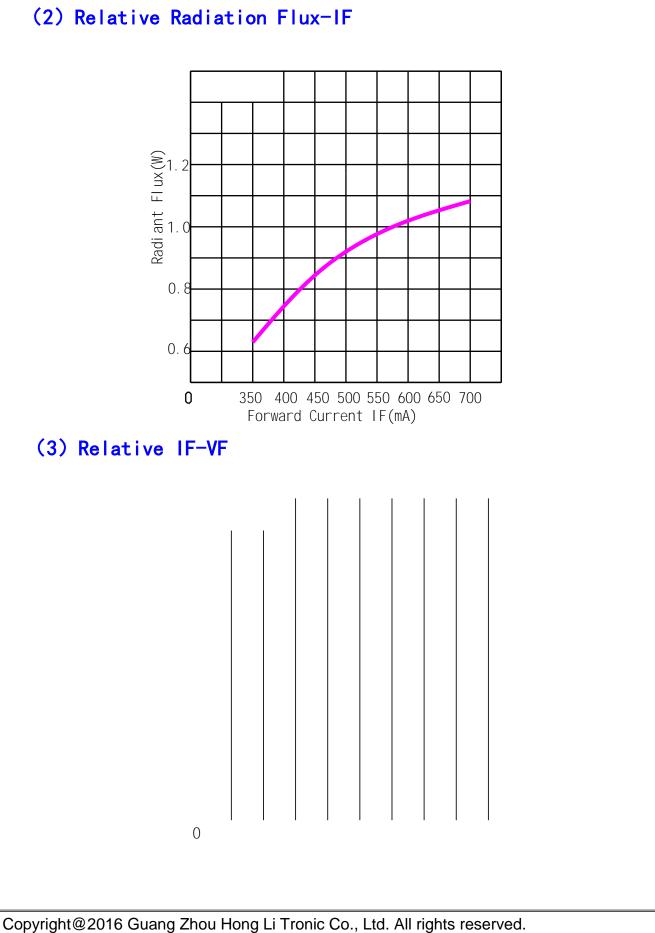
ltem名称	Symbol 符号	Absolute Maximum Rating 绝对最大额定值	Units
Power dissipation	Pd	2.8	W
R Peak Forward Current	I _{Fp}	700	mA
Reverse Voltage	V _R	5	V

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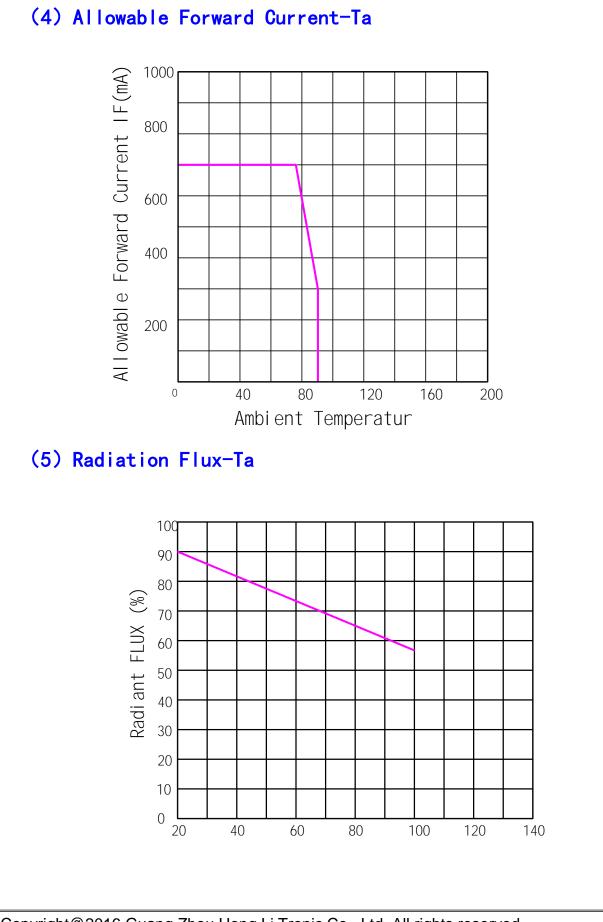






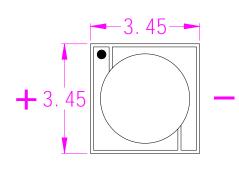


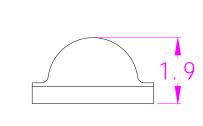


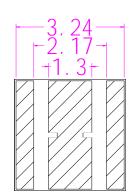




Package Dimensions





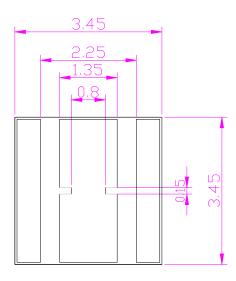


Notes

1. All dimension units are millimeters.

 ± 0.1

Welded plate Dimensions



Notes :

When the circuit configuration is not affected, suggested the increase in the middle of the copper area, or the connection between the middle and the pad and the negative electrode can improve the cooling performance of the product It is recommended to use 1 mmthickness of steel mask.

1mm





Label

TYPE: XXXXXXXXX

QTY: XXXXX

VF: Forward voltage rank

e: Radiation Flux rank

IF: XXXX

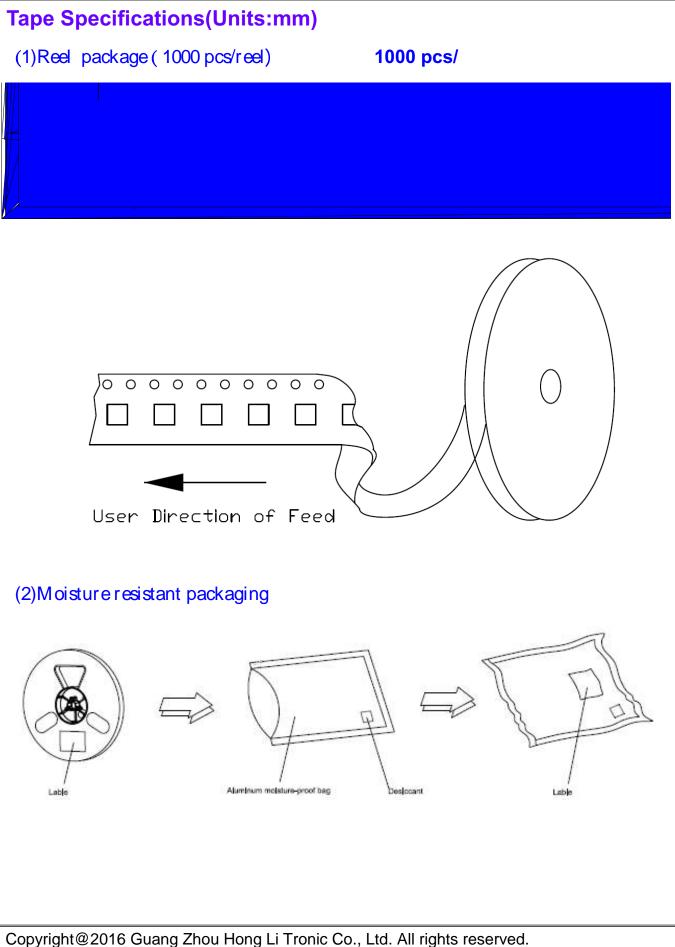
P: Peak Wavelength

DATE: XXXX

LOT.NO:Lot Number

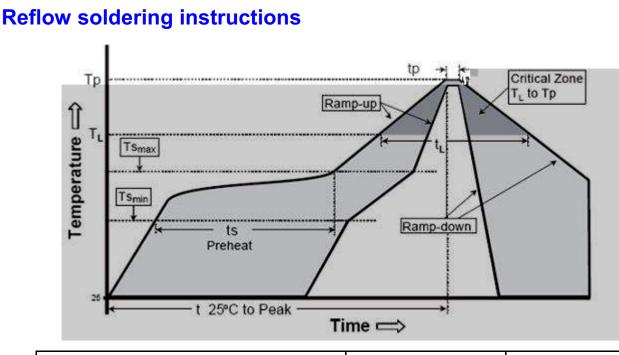
1	HONGLITRONIC 鸿利光电	RoHS
TYPE: VF: IF: DATE		QTY: : LOT. NO:











Profile Feature	Lead-Based solder	Lead-Free Solder
Average Ramp-Rate (Ts _{max} to Tp)	3 /second max	3 /second max
Preheat: Temperature Min (Ts _{min})	100	150
Preheat:Temperature Max (Ts _{max})	150	200
Preheat:Time(ts _{min} to ts _{max})	60-120 seconds	60-180 seconds
Time Maintained Above: Temperature(T_L)	183	217
Time Maintained Above: Time(t _L)	60-150 seconds	60-150 seconds
Peak/Classification Temperature(Tp)	215	260
Time Within 5 of Actual Peak Temperature(tp)	10-15 seconds	20-40 seconds
Ramp-Down Rate	6 /second max	6 /second max
Time 25 to Peak Temperature	6 minutes max	8 minutes max

Note:

1.recommend to use a convection type reflow machine with 8 zones.

n min

2.recommend to use Lead-Free Paste with a melting point between

3.the reflow soldering time should not be more than 360s.all temperature means the temperature measured on the surface of the package body.

360s

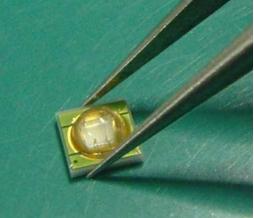
4. When using hot plate, the temperature is no more than 260 $\,$, the time is not more than 5 seconds. 260 $\,$ 5

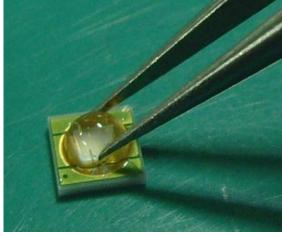


Use the matters needing attention(使用注意事项) (stor g 0 °±° o voi moistur w r omm n storg on itions for th unop n ~ ° r l tiv hu shoul us within rsofopningth pkg lsmksur to mi ity hu °±° mi ify n v uump kth r m ining unus humi ifying on ition rs ff tiv g for th s I I ison y r (th ss m ly not s o g ol ring on itions his prout must us r flow sol ring pr ti s th m ximum t mp r tur of r flow shoul not x ° Is m k sur wh n sol ring th r is no xt rn I for on th sol ring sur sub sprssur frition or sh rpm t ln ils t to voi gol wir form tion or m g n f oth r norm litis f yon romm n on itions w nnot gurnt th st ility pl s oth risk ss ss m nt first (ntit ti sur s) qut m sur stopr v nt l trost ti g n r tion su h s w ring l trost ti ring or lstk ntist ti fing rst II t nyr I tiv pro u ts lik pl nt quipm nt m hin ry rri r n tr nsport tion-unitsshll onn t to is hrging-unit groun ftr-ssmlyplsmk-sur-to-is-hrg t ti l tri ity with prop r quipm nt (t mp r tur ontrol)



uring ssm lypl s nsur tht goo quility thrm lpst is ppli vnlyovrth sur n istriut tink m k sur hil using thrm lp isfirmly tight n f n thr is nogp tw nsur to nsur the ooling m ium il tri withst n t st tl st through f s h n (riv ontrol Drive this product at constant current. Output current range specifications should be according to the operational and other conditions, as mentioned in data sheet. Before using a constant voltage source or altered specifications, other than recommended, please consider risk factors. (oth r Т х х ro u t is not suit I to us in following on itions ir torin ir tw.t mp on itions su h sr in t -in ont twiths wtrn rosiv mtrils to orrosiv gss g x t xpos Х to ust liqui soroils xpos





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Notes注:

1.* All high power emitter LED products mounted on aluminum metal-core printed circuit board, can be lighted directly, but we do not recommend lighting the high power products for more than 5 seconds without a appropriate heat dissipation equipment. LED

	1	LED	5		
2.Reflow soldering should not be done more than two times. The reflow temperature we recommend is					
260°C,When the temperature exceeds 260 , the product failure of LED can be caused					
	I	:	260	260	LED .